

HAOPIN MICROELECTRONICS CO., LTD.

Description

Passivated high commutation triacs in a plastic envelope intended for use in circuits where high static and dynamic dV/dt and high di/dt can occur. These devices will commutate the full rated ms current at the maximum rated junction temperature without the aid of a snubber.

Symbol	Simplified outline
	 TO-220
Pin	Description
1	Main terminal 1 (T1)
2	Main terminal 2 (T2)
3	gate (G)
TAB	isolated

Applications:

- ◆ Motor control
- ◆ Industrial and domestic lighting
- ◆ Heating
- ◆ Static switching

Features

- ◆ Blocking voltage to 600 V
- ◆ On-state RMS current to 16 A

SYMBOL	PARAMETER	Value	Unit
V_{DRM}	Repetitive peak off-state voltages	600	V
$I_T \text{ (RMS)}$	RMS on-state current (full sine wave)	16	A
I_{TSM}	Non-repetitive peak on-state current (full cycle, T_j initial=25°C)	170	A

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
$R_{th(j-c)}$	Junction to case(AC)		—	2.1	—	°C/W
$R_{th(j-a)}$	Junction to ambient ($s=1 \text{ cm}^2$)		—	60	—	°C/W



T1635T-6I

Three quadrant triacs

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Limiting values in accordance with the Maximum system(IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN	Value	UNIT
V_{DRM}/V_{RRM}	Repetitive peak off-state Voltages		-	600	V
$I_{T(RMS)}$	on-state rms current	Full sine wave; $T_c=86^\circ\text{C}$	-	16	A
I_{TSM}	Non repetitive surge peak on-state current	full cycle, $T_j \text{ initial} = 25^\circ\text{C}$	$F=50\text{Hz}$ $F=60\text{Hz}$	$t=20\text{ms}$	120
				$t=16.7\text{ms}$	126
I^2t	I^2t value for fusing		$tp=10\text{ms}$	-	A^2s
dI/dt	Critical rate of rise of on-state current	$I_G=2 \times I_{GT}$ $tr \leq 100\text{ns}$	$F=60\text{Hz}$ $T_j=125^\circ\text{C}$	-	$50/\mu\text{s}$
I_{GM}	Peak gate current		$tp=20\mu\text{s}$ $T_j=125^\circ\text{C}$	-	4
$P_{G(AV)}$	Average gate power dissipation		$T_j=125^\circ\text{C}$	-	1
T_{stg}	Storage junction temperature range		-40	150	$^\circ\text{C}$
T_j	Operating junction temperature range		-40	125	$^\circ\text{C}$

 $T_j=25^\circ\text{C}$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
Static characteristics						
I_{GT} V_{GT}	$V_D=12\text{V}$; $RL=30\Omega$ $V_D=V_{DRM}$, $RL=3.3\text{K}\Omega$	$T_j=25^\circ\text{C}$	I-II-III ALL	- -	35 1.3	mA V
I_L	$I_G=1.2 I_{GT}$	$T_j=25^\circ\text{C}$	I-III II	- -	50 80	mA mA
$I_H(2)$	$I_T=500\text{mA}$		-	-	40	mA
V_{GD}	$V_D=V_{DRM}$ $R_L=3.3\text{K}\Omega$	$T_j=125^\circ\text{C}$	ALL	0.2	-	-
$dV/dt(2)$	$V_D=67\%V_{DRM}$ gate open	$T_j=125^\circ\text{C}$ $T_j=150^\circ\text{C}^{(3)}$	2000 1000	-	-	$\text{V}/\mu\text{s}$
$(dI/dt)c(2)$	Without snubber	$T_j=125^\circ\text{C}$ $T_j=150^\circ\text{C}^{(3)}$	16 12	-	-	A/ms

Dynamic Characteristics

$V_T^{(1)}$ $V_{TO}^{(1)}$	$I_{TM}=22.6\text{A}$ $tp=380\mu\text{s}$ Threshold voltage	$T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$	-	-	1.55 0.85	V
I_{DRM} I_{RRM}	$V_{DRM}=V_{RRM}$ $V_D=0.9 \times V_{RRM}$	$T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$ $T_j=150^\circ\text{C}^{(2)}$	-	-	5 1 1.9	μA mA mA

Note1:minimum I_{GT} is guaranteed at 5% of I_{GT} max.

Note2: for both polarities of A2 referenced to A1.

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Figure 1. Maximum power dissipation versus rms on-state current (full cycle)

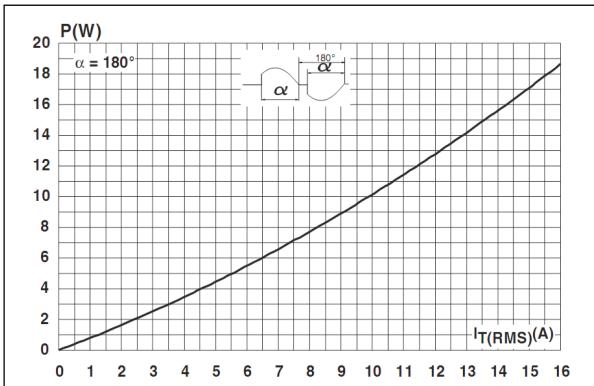


Figure 2. On-state rms current versus case temperature (full cycle)

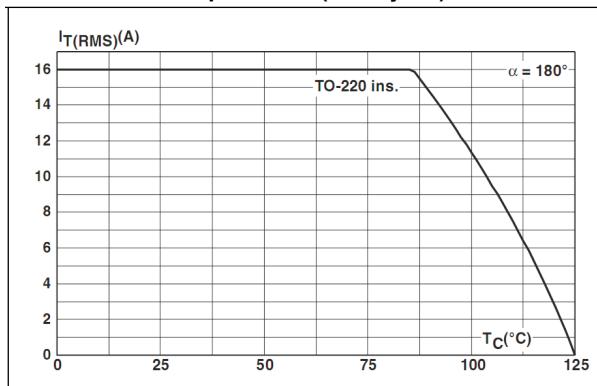


Figure 3. On-state rms current versus ambient temperature

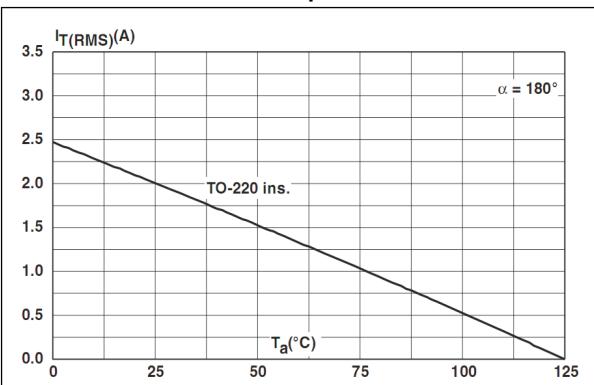


Figure 4. Relative variation of thermal impedance versus pulse duration

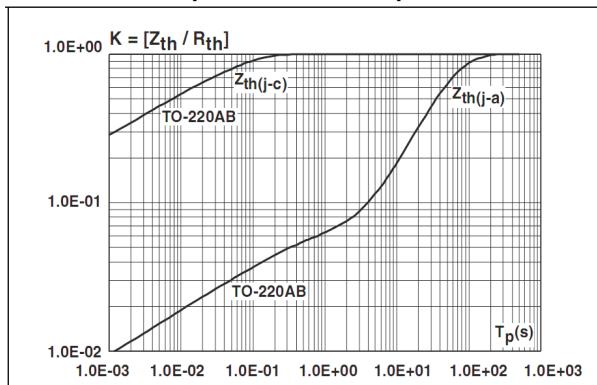


Figure 5. On state characteristics (maximum values)

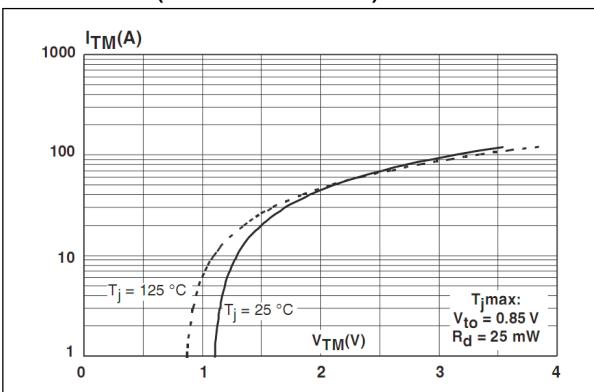
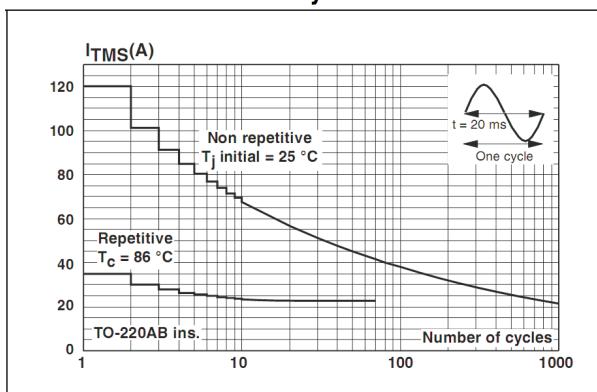


Figure 6. Surge peak on state current versus number of cycles



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Figure 7. Non repetitive surge peak on state current for a sinusoidal

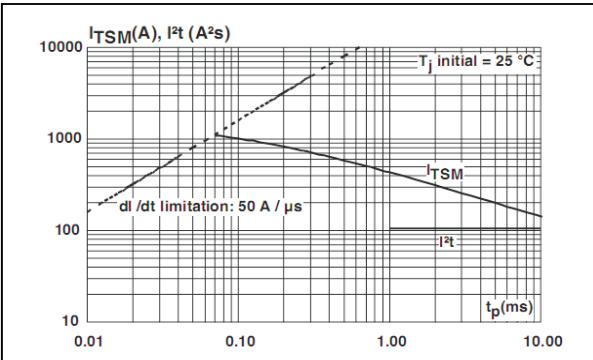


Figure 8. Relative variation of gate trigger current and gate trigger voltage versus junction temperature

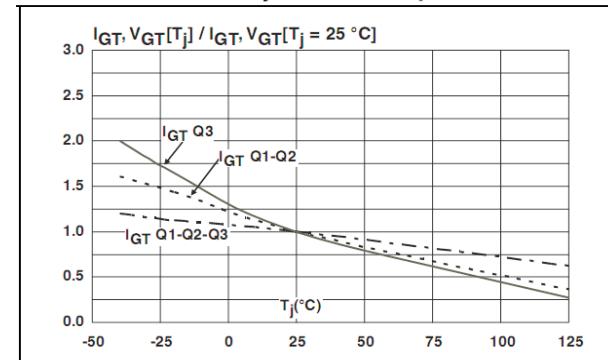


Figure 9. Relative variation of holding current and latching current versus junction temperature

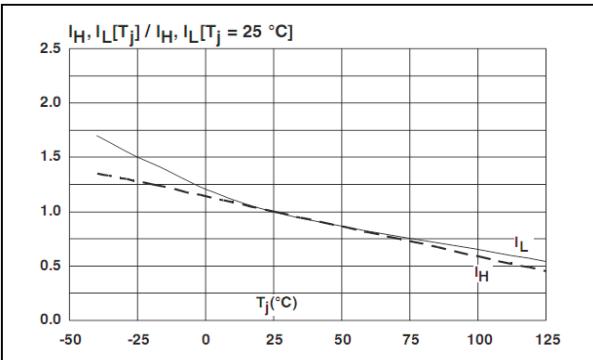


Figure 10. Relative variation of critical rate of decrease of main current versus junction temperature

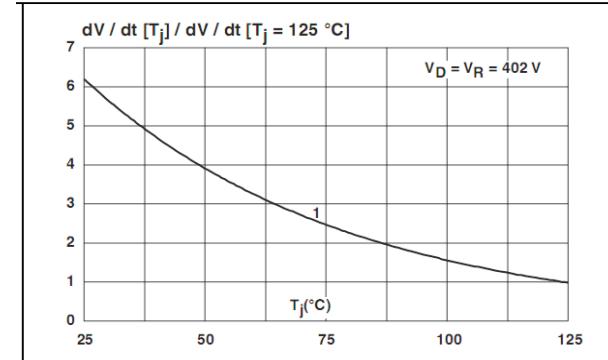


Figure 11. Relative variation of critical rate of decrease of main current versus junction temperature

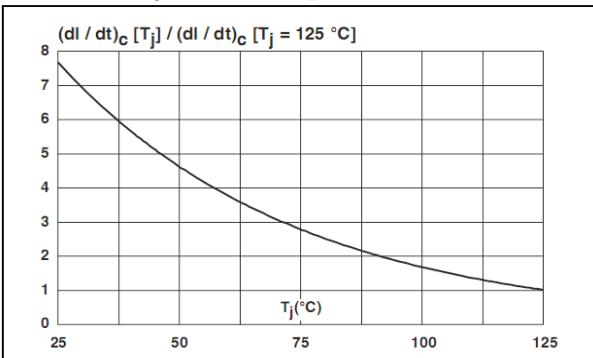
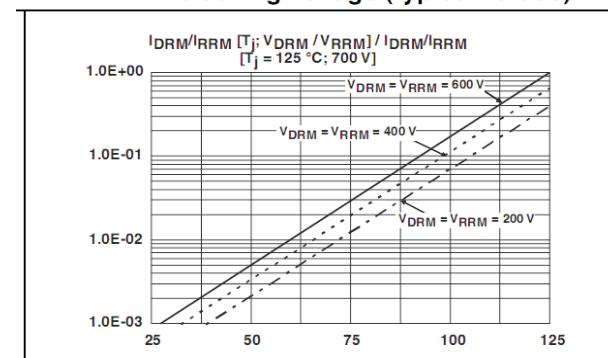
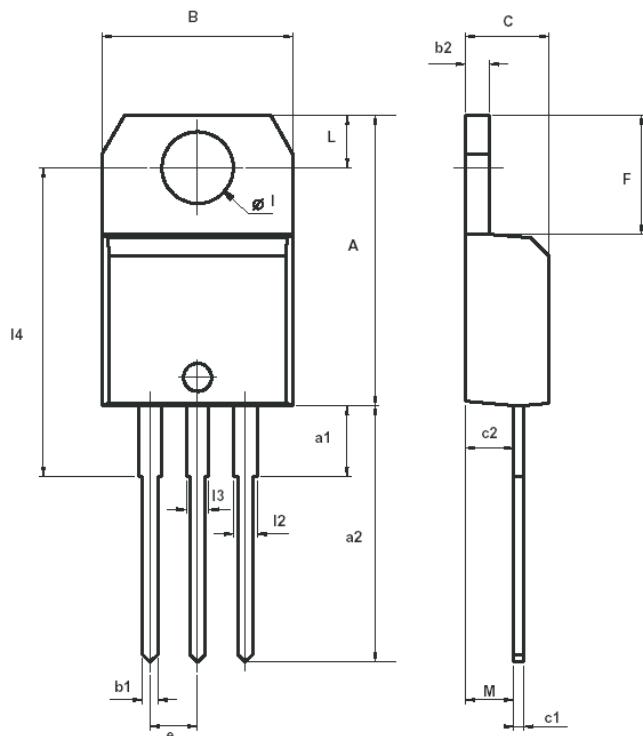


Figure 12. Leakage current versus junction temperature for different values of blocking voltage (typical values)



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MECHANICAL DATA

Dimensions in mm
Net Mass: 2 g
TO-220



REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	15.20		15.90	0.598		0.625
a1		3.75			0.147	
a2	13.00		14.00	0.511		0.551
B	10.00		10.40	0.393		0.409
b1	0.61		0.88	0.024		0.034
b2	1.23		1.32	0.048		0.051
C	4.40		4.60	0.173		0.181
c1	0.49		0.70	0.019		0.027
c2	2.40		2.72	0.094		0.107
e	2.40		2.70	0.094		0.106
F	6.20		6.60	0.244		0.259
I	3.75		3.85	0.147		0.151
l4	15.80	16.40	16.80	0.622	0.646	0.661
L	2.65		2.95	0.104		0.116
l2	1.14		1.70	0.044		0.066
l3	1.14		1.70	0.044		0.066
M		2.60			0.102	